General Purpose Transistor

NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	40	Vdc
Collector - Base Voltage	V _{CBO}	60	Vdc
Emitter-Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	Ic	200	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

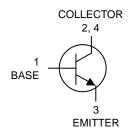
Characteristic	Symbol	Max	Unit
Total Device Dissipation (Note 1) T _A = 25°C	P _D	1.5 12	W mW/°C
Thermal Resistance Junction–to–Ambient (Note 1)	$R_{\theta JA}$	83.3	°C/W
Thermal Resistance Junction-to-Lead #4	$R_{\theta JA}$	35	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

^{1.} FR-4 with 1 oz and 713 mm² of copper area.



ON Semiconductor®

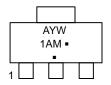
http://onsemi.com





SOT-223 CASE 318E STYLE 1

MARKING DIAGRAM



1AM = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

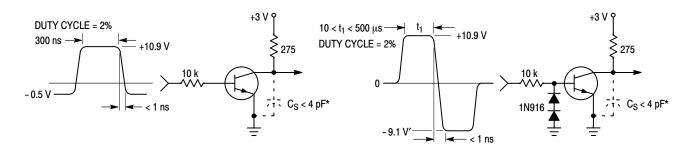
Device	Package	Shipping [†]
PZT3904T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
SPZT3904T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Chara	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS (Note 2)					
Collector - Emitter Breakdown Voltage (No	V _{(BR)CEO}	40	_	Vdc	
Collector – Base Breakdown Voltage (I _C = 10 μAdc, I _E = 0)			60	_	1
Emitter-Base Breakdown Voltage (I _E = 1	V _{(BR)EBO}	6.0	_	1	
Base Cutoff Current (V _{CE} = 30 Vdc, V _{EB} =	I _{BL}	-	50	nAdc	
Collector Cutoff Current (V _{CE} = 30 Vdc, V	I _{CEX}	_	50	1	
ON CHARACTERISTICS (Note 3)			-		
$\begin{array}{l} \text{DC Current Gain (Note 2)} \\ (I_{C} = 0.1 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ (I_{C} = 1.0 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ (I_{C} = 10 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ (I_{C} = 50 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ (I_{C} = 100 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \end{array}$		H _{FE}	40 70 100 60 30	- 300 - -	-
Collector – Emitter Saturation Voltage (Note 3) $ (I_{C} = 10 \text{ mAdc}, I_{B} = 1.0 \text{ mAdc}) $ $ (I_{C} = 50 \text{ mAdc}, I_{B} = 5.0 \text{ mAdc}) $				0.2 0.3	Vdc
$\begin{aligned} &\text{Base-Emitter Saturation Voltage (Note 3}\\ &\text{(I}_{\text{C}} = 10 \text{ mAdc, I}_{\text{B}} = 1.0 \text{ mAdc)}\\ &\text{(I}_{\text{C}} = 50 \text{ mAdc, I}_{\text{B}} = 5.0 \text{ mAdc)} \end{aligned}$	V _{BE(sat)}	0.65	0.85 0.95	Vdc	
SMALL-SIGNAL CHARACTERISTICS		•	•	•	•
Current-Gain - Bandwidth Product (I _C =	10 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	f _T	300	-	MHz
Output Capacitance ($V_{CB} = 5.0 \text{ Vdc}$, $I_{E} =$	0, f = 1.0 MHz)	C _{obo}	-	5.0	pF
Input Capacitance ($V_{EB} = 0.5 \text{ Vdc}$, $I_{C} = 0$,	f = 1.0 MHz)	C _{ibo}	-	8.0	
Input Impedance ($V_{CE} = 10 \text{ Vdc}$, $I_{C} = 1.0$	mAdc, f = 1.0 kHz)	h _{ie}	1.0	10	kΩ
Voltage Feedback Ratio (V _{CE} = 10 Vdc, I _C	C = 1.0 mAdc, f = 1.0 kHz)	h _{re}	0.5	8.0	X 10 ⁻⁴
Small-Signal Current Gain (V _{CE} = 10 Vd	h _{fe}	100	400	-	
Output Admittance ($V_{CE} = 10 \text{ Vdc}, I_{C} = 1.$	h _{oe}	1.0 40 μMI		μMhos	
Noise Figure (V_{CE} = 5.0 Vdc, I_{C} = 100 μ A	nF	_	5.0	dB	
SWITCHING CHARACTERISTICS					
Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = -0.5 \text{ Vdc},$	t _d	_	35	ns
Rise Time	$I_C = 10 \text{ mAdc}, I_{B1} = 1.0 \text{ mAdc})$	t _r	_	35	1
Storage Time	(V _{CC} = 3.0 Vdc,	t _s	-	200	1
Fall Time	$I_C = 10 \text{ mAdc}, I_{B1} = I_{B2} = 1.0 \text{ mAdc})$	t _f	_	50	1

- 2. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

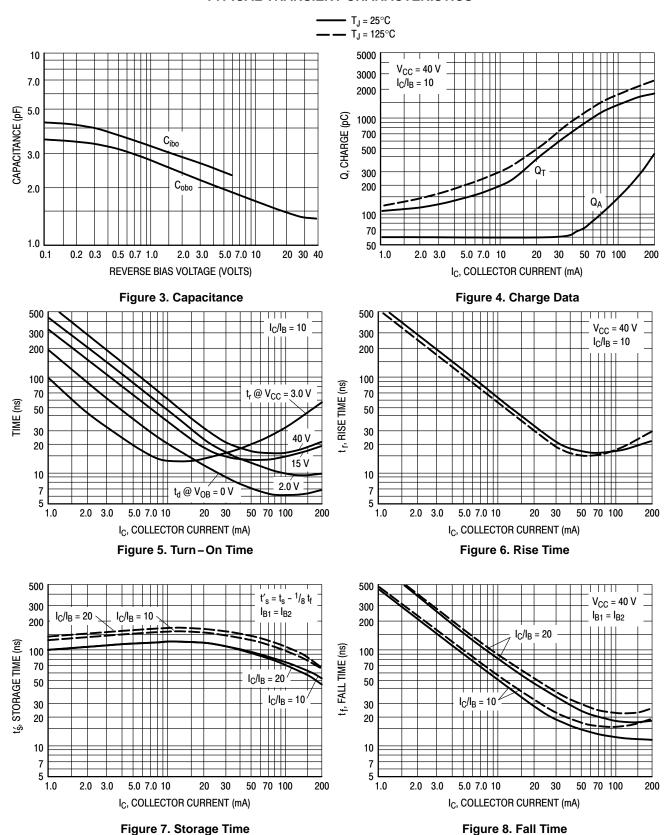


^{*} Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

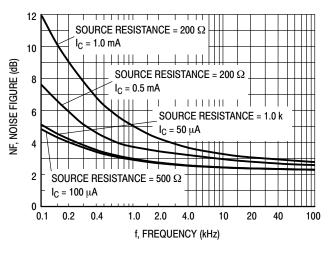
Figure 2. Storage and Fall Time Equivalent Test Circuit

TYPICAL TRANSIENT CHARACTERISTICS



TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth} = 1.0 \text{ Hz})$



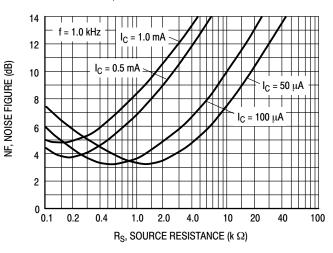
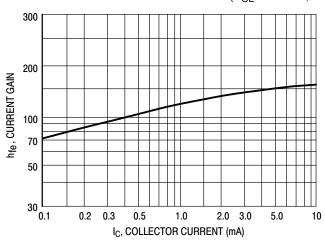


Figure 9.

Figure 10.

h PARAMETERS

 $(V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$



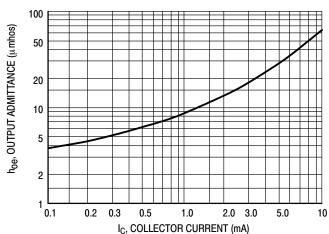
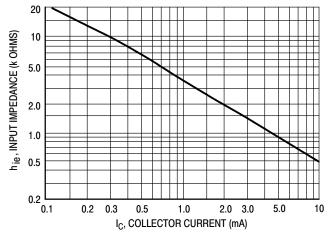


Figure 11. Current Gain

Figure 12. Output Admittance



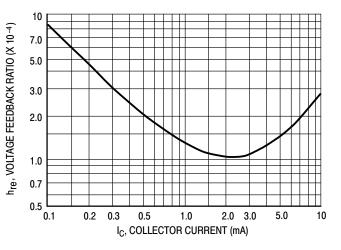


Figure 13. Input Impedance

Figure 14. Voltage Feedback Ratio

TYPICAL STATIC CHARACTERISTICS

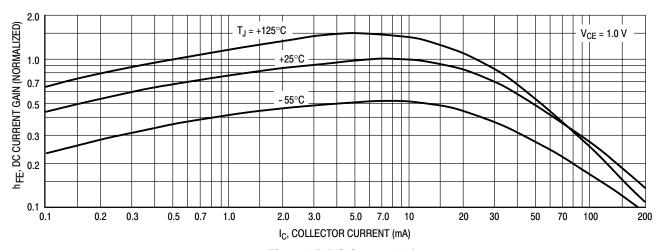


Figure 15. DC Current Gain

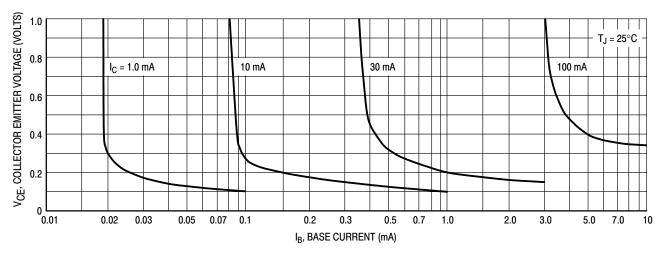


Figure 16. Collector Saturation Region

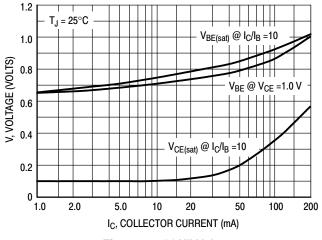


Figure 17. "ON" Voltages

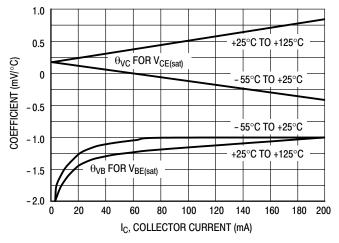


Figure 18. Temperature Coefficients

TYPICAL CHARACTERISTICS

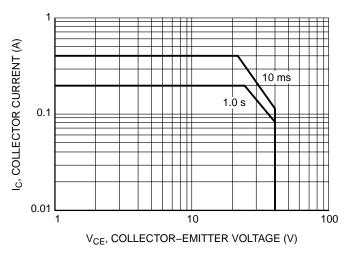
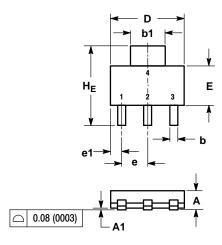
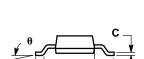


Figure 19. Safe Operating Area

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE N





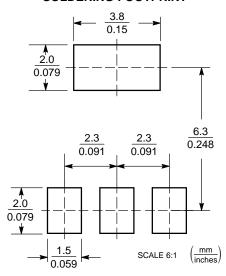
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
C	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
Г	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	_	10°	0°	_	10°

STYLE 1:

- PIN 1. BASE 2. COLLECTOR
 - 3 FMITTER
 - COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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